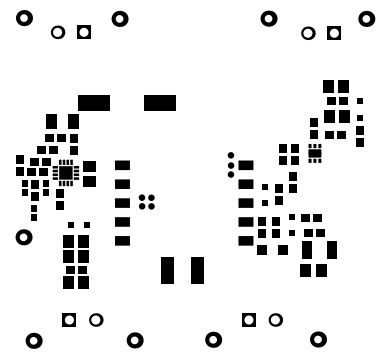
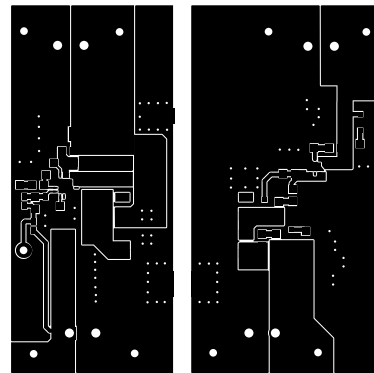


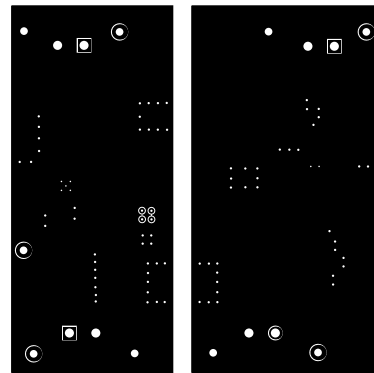
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #:		
PLOT NAME = Top Overlay	GENERATED : 12/12/2016 9:23:38 AM	TEXAS INSTRUMENTS	



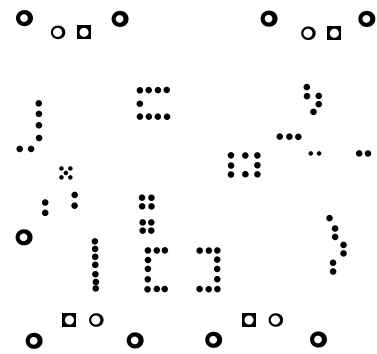
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #:		
PLOT NAME = Top Solder Mask	GENERATED : 12/12/2016 9:23:39 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #:		
PLOT NAME = Top Layer	GENERATED : 12/12/2016 9:23:40 AM	TEXAS INSTRUMENTS	



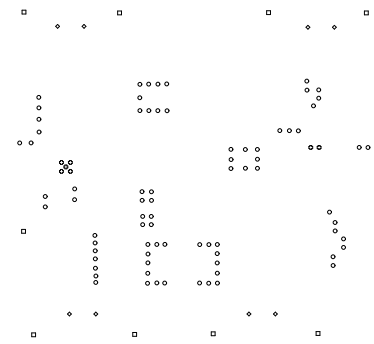
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #:		
PLOT NAME = Bottom Layer	GENERATED : 12/12/2016 9:23:41 AM	TEXAS INSTRUMENTS	



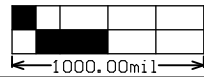
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #:		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/12/2016 9:23:42 AM	TEXAS INSTRUMENTS	

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #:		
PLOT NAME = Bottom Overlay	GENERATED : 12/12/2016 9:23:43 AM	TEXAS INSTRUMENTS	

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
⊕	7	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>			
◇	8	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	<Mixed>	<Mixed>			
□	9	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c203h102			
○	77	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	<Mixed>			
	101 Total										



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #:		
PLOT NAME = Drill Drawing	GENERATED : 12/12/2016 9:23:44 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20550	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #:		
PLOT NAME = Board Dimensions	GENERATED : 12/12/2016 9:23:45 AM	TEXAS INSTRUMENTS	

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